

## Notice of References Cited

Application/Control No.  
09/838,493Applicant(s)/Patent Under  
Re-examinationExaminer  
Khiem D NguyenArt Unit  
2823

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*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
A	US-6,261,954	07-2001	Ho et al.	438/687
B	US-			
C	US-			
D	US-			
E	US-			
F	US-			
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I	US-			
J	US-			
K	US-			
L	US-			
M	US-			

## FOREIGN PATENT DOCUMENTS

*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
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T					

## NON-PATENT DOCUMENTS

Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)

U	U.S. 2002/0100693 Electrochemical Reduction of Copper Seed for reducing ECD Voids Aug. 1, 2002.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
 Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.